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ABSTRACT

A method of mounting a semiconductor device (16) comprises the steps of disposing an anisotropic conductive adhesive (13) on the surface of a circuit board (17), placing the semiconductor device (16) on the surface of the circuit board (17) after aligning bumps (14) provided on the semiconductor device (16) with wiring patterns (15) formed on the surface of the circuit board (17), respectively, provisionally press-bonding the semiconductor device (16) onto the circuit board (17) by heating at a temperature lower than the curing temperature of an adhesive resin (11) of the anisotropic conductive adhesive (13) while applying a predetermined pressure thereto by use of a heating and pressurizing tool (18), and thereafter bonding the semiconductor device (16), as provisionally press-bonded, onto the circuit board (17) by heating and curing the adhesive resin (11) at a temperature causing the same to be cured.